



ProLight PM2A-1Lxx 1W Power LED Technical Datasheet Version: 1.6

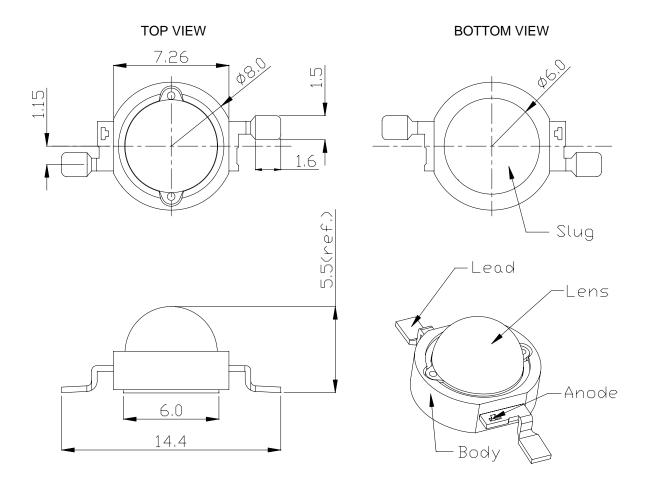
Features

- High flux per LED
- Various colors
- Good color uniformity
- RoHS compliant
- More energy efficient than incandescent and most halogen lamps
- Low Voltage DC operated
- Instant light (less than 100ns)
- No UV
- Superior ESD protection

Typical Applications

- Reading lights (car, bus, aircraft)
- Portable (flashlight, bicycle)
- Uplighters/Downlighters
- Decorative/Entertainment
- Bollards/Security/Garden
- Cove/Undershelf/Task
- Indoor/Outdoor Commercial and Residential Architectural
- Automotive Ext (Stop-Tail-Turn, CHMSL, Mirror Side Repeat)
- LCD backlights

Emitter Mechanical Dimensions

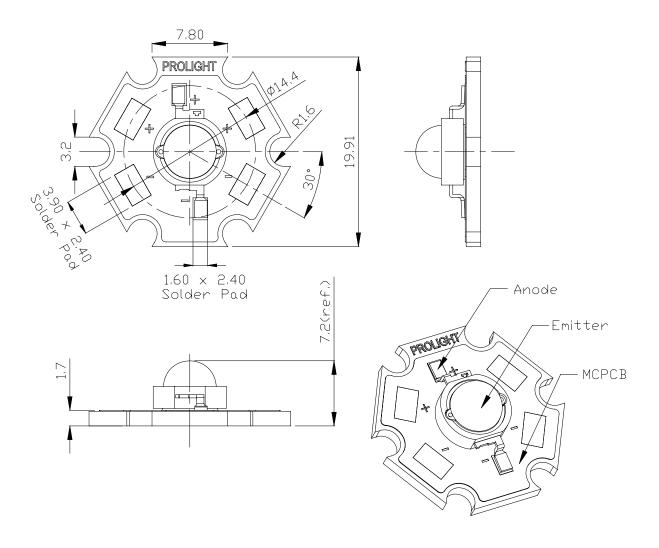


Notes:

- 1. The Anode side of the device is denoted by a hole in the lead frame.
- 2. Electrical insulation between the case and the board is required --- slug of device is not electrically neutral. Do not electrically connect either the anode or cathode to the slug.
- 3. Drawing not to scale.
- 4. All dimensions are in millimeters.
- 5. All dimendions without tolerances are for reference only.
- 6. Please do not bend the leads of the LED, otherwise it will damage the LED.
- 7. Please do not use a force of over 3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.

^{*}The appearance and specifications of the product may be modified for improvement without notice.

Star Mechanical Dimensions



Notes:

- 1. Slots in aluminum-core PCB for M3 or #4 mounting screw.
- 2. Electrical interconnection pads labeled on the aluminum-core PCB with "+" and "-" to denote positive and negative, respectively. All positive pads are interconnected, as are all negative pads, allowing for flexibility in array interconnection.
- 3. Drawing not to scale.
- 4. All dimensions are in millimeters.
- 5. All dimendions without tolerances are for reference only.
- 6. Please do not use a force of over 3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.

^{*}The appearance and specifications of the product may be modified for improvement without notice.

Flux Characteristics at 350mA, $T_J = 25$ °C

Radiation	Colon	Part N	umber	Lumious Flux Φ_{V} (lm)	
Pattern	Color	Emitter	Star	Minimum	Typical
	White	PM2A-1LWE	PM2A-1LWS	76.6	90
	Warm White	PM2A-1LVE	PM2A-1LVS	67.2	81
Lambertian	Green	PM2A-1LGE	PM2A-1LGS	58.9	70
Lambordan	Blue	PM2A-1LBE	PM2A-1LBS	10.7	14
	Amber	PM2A-1LAE	PM2A-1LAS	30.6	42
	Red	PM2A-1LRE	PM2A-1LRS	30.6	40

- ProLight maintains a tolerance of ± 10% on flux and power measurements.
- Please do not drive at rated current more than 1 second without proper heat sink.

Electrical Characteristics at 350mA, T_J = 25°C

	Forwa	rd Voltage	V _F (V)	Dynamic	Temperature Coefficient of V _F (mV/ °C)	Thermal Resistance Junction to
Color	Min.	Тур.	Max.	Resistance (Ω)	$\Delta V_F / \Delta T_J$	Slug (°C/W)
White	2.85	3.5	4.1	1.0	-2.0	10
Warm White	2.85	3.5	4.1	1.0	-2.0	10
Green	2.85	3.5	4.1	1.0	-2.0	10
Blue	2.85	3.5	4.1	1.0	-2.0	10
Amber	1.75	2.2	3.0	2.4	-2.0	10
Red	1.75	2.2	3.0	2.4	-2.0	10

Optical Characteristics at 350mA, T_J = 25°C

Radiation Pattern	Color		nt Wavele Temperat Typ.	O D,	Spectral Half-width (nm) Δλ _{1/2}	Temperature Coefficient of Dominant Wavelength (nm/ °C) Δλ _D / ΔΤ _L	Total included Angle (degrees) $\theta_{0.90V}$	Viewing Angle (degrees) 2 θ _{1/2}
- attern	White	4100 K	5500 K	10000 K			180	130
	Warm White	2700 K	3300 K	4100 K			180	130
Lambertian	Green	515 nm	525 nm	535 nm	35	0.04	180	130
Lambertian	Blue	455 nm	465 nm	475 nm	25	0.04	180	130
	Amber	587 nm	592 nm	597 nm	20	0.05	180	130
	Red	613.5 nm	623 nm	631 nm	20	0.05	180	130

- ProLight maintains a tolerance of ± 1nm for dominant wavelength measurements.
- ProLight maintains a tolerance of ± 5% for CCT measurements.

Absolute Maximum Ratings

Parameter	White/Warm White/ Green/Blue/Amber/Red	
DC Forward Current (mA)	350	
Peak Pulsed Forward Current (mA)	500	
Average Forward Current (mA)	350	
ESD Sensitivity (HBM per MIL-STD-883E Method 3015.7)	±4000V (Class III)	
LED Junction Temperature (°C)	120	
Aluminum-core PCB Temperature (°C)	105	
Storage & Operating Temperature (°C)	-40 to +105	
Soldering Temperature(°C)	235°C	

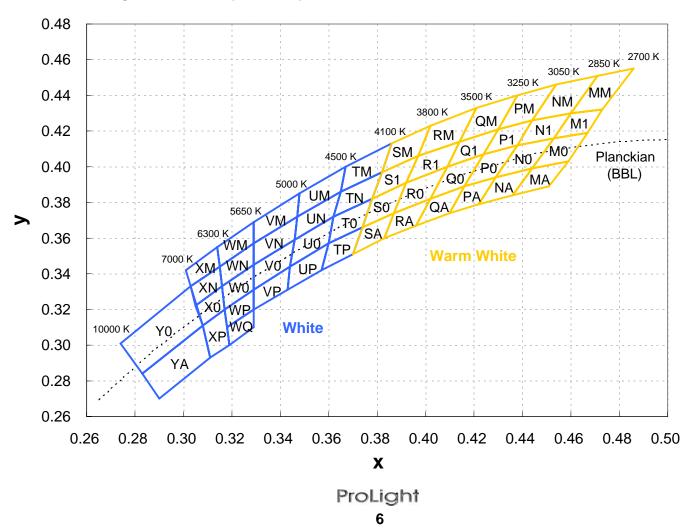
Photometric Luminous Flux Bin Structure

Color	Bin Code	Minimum Photometric Flux (Im)	Maximum Photometric Flux (Im)
White	T2	76.6	87.4
VVIIIC	U1	87.4	99.6
	T1	67.2	76.6
Warm White	T2	76.6	87.4
waiiii wiiile	U1	87.4	99.6
	*When C	CT is less than 3050K, U1 bin is not ava	ailable.
	S2	58.9	67.2
Green	T1	67.2	76.6
	T2	76.6	87.4
	L	10.7	13.9
Blue	M	13.9	18.1
	N	18.1	23.5
	Q	30.6	39.8
Amber	R	39.8	51.7
	S1	51.7	58.9
	Q	30.6	39.8
Red	R	39.8	51.7
	S1	51.7	58.9

- \bullet ProLight maintains a tolerance of \pm 10% on flux and power measurements.
- The flux bin of the product may be modified for improvement without notice.

Color Bin

White and Warm White Binning Structure Graphical Representation



Color Bins

White Bin Structure

Bin Code	x	у	Typ. CCT (K)	Bin Code	x	у	Typ. CCT (K)
	0.378	0.382			0.329	0.345	
T0	0.374	0.366	4300	WO	0.329	0.331	5970
10	0.360	0.357	4000	****	0.317	0.320	0010
	0.362	0.372			0.316	0.333	
	0.382	0.397			0.329	0.345	
TN	0.378	0.382	4300	WN	0.316	0.333	5970
	0.362	0.372			0.315	0.344	
	0.365	0.386			0.329	0.357	
	0.374	0.366			0.329	0.331	
TP	0.370 0.357	0.351 0.342	4300	WP	0.329 0.318	0.320 0.310	5970
	0.357	0.342			0.316	0.310	
		0.337			0.329	0.320	
	0.386 0.382	0.413			0.329	0.320	
TM	0.362	0.386	4300	WQ	0.329	0.310	5970
	0.367	0.400			0.318	0.310	
	0.362	0.372			0.329	0.369	
	0.362	0.372			0.329	0.357	
U0	0.344	0.344	4750	750 WM	0.329	0.344	5970
	0.346	0.359			0.314	0.355	
	0.365	0.386			0.308	0.311	
	0.362	0.372			0.305	0.322	
UN	0.346	0.359	4750	X0	0.316	0.333	6650
	0.347	0.372			0.317	0.320	
	0.360	0.357			0.305	0.322	
LID	0.357	0.342	4750	VAI	0.303	0.333	0050
UP	0.343	0.331	4750	XN	0.315	0.344	6650
	0.344	0.344			0.316	0.333	
	0.365	0.386			0.308	0.311	
UM	0.367	0.400	4750	XP	0.317	0.320	6650
Olvi	0.348	0.385	4750	ΛΓ	0.319	0.300	0030
	0.347	0.372			0.311	0.293	
	0.329	0.331			0.301	0.342	
V0	0.329	0.345	5320	XM	0.314	0.355	6650
VO	0.346	0.359	3320	XIVI	0.315	0.344	0000
	0.344	0.344			0.303	0.333	
	0.329	0.345			0.308	0.311	
VN	0.329	0.357	5320	Y0	0.283	0.284	8000
• • • • • • • • • • • • • • • • • • • •	0.347	0.372	0020	. 0	0.274	0.301	0000
	0.346	0.359			0.303	0.333	
	0.329	0.331			0.308	0.311	
VP	0.344	0.344	5320	YA	0.311	0.293	8000
	0.343	0.331	-		0.290	0.270	
	0.329	0.320			0.283	0.284	
	0.329	0.357					
VM	0.329	0.369	5320				
	0.348	0.385					
	0.347	0.372					

 $[\]bullet$ Tolerance on each color bin (x , y) is \pm 0.01

Color Bins

Warm White Bin Structure

Bin Code	x	у	Typ. CCT (K)	Bin Code	x	у	Typ. CCT (K)
	0.453	0.416			0.409	0.400	
MO	0.444	0.399	2770	Q0	0.402	0.382	3370
IVIO	0.459	0.403	2110	QU	0.416	0.389	3370
	0.467	0.419			0.424	0.407	
	0.460	0.430			0.414	0.414	
M1	0.453	0.416	2770	Q1	0.409	0.400	3370
141.1	0.467	0.419	2170	Q i	0.424	0.407	0010
	0.473	0.432			0.430	0.421	
	0.459	0.403			0.416	0.389	
MA	0.444	0.399	2770	QA	0.402	0.382	3370
1717 (0.436	0.384	2170	Q/ (0.396	0.367	0010
	0.451	0.389			0.410	0.374	
	0.471	0.451			0.421	0.433	
MM	0.460	0.430	2770	QM	0.414	0.414	3370
141141	0.473	0.432	2170	QIVI	0.430	0.421	0010
	0.486	0.455			0.438	0.440	
	0.438	0.412			0.392	0.391	
N0	0.429	0.394	2950	R0	0.387	0.374	3650
140	0.444	0.399	2550	NO	0.402	0.382	3030
	0.453	0.416			0.409	0.400	
	0.444	0.426			0.414	0.414	
N1	0.438	0.412	2950	R1	0.409	0.400	3650
INI	0.453	0.416	2930	IXI	0.392	0.391	0000
	0.460	0.430			0.397	0.406	
	0.444	0.399			0.387	0.374	
NA	0.429	0.394	2950	RA	0.383	0.360	3650
INA	0.422	0.379	2930	IXA	0.396	0.367	3030
	0.436	0.384			0.402	0.382	
	0.454	0.446			0.421	0.433	
NM	0.444	0.426	2950	RM	0.414	0.414	3650
INIVI	0.460	0.430	2930	IXIVI	0.397	0.406	3030
	0.471	0.451			0.402	0.423	
	0.424	0.407			0.392	0.391	
P0	0.416	0.389	3150	S0	0.387	0.374	3950
FU	0.429	0.394	3130	30	0.374	0.366	3930
	0.438	0.412			0.378	0.382	
	0.430	0.421			0.397	0.406	
P1	0.424	0.407	3150	S1	0.392	0.391	3950
FI	0.438	0.412	3130	31	0.378	0.382	3930
	0.444	0.426			0.382 0.387	0.397	
	0.429	0.394			0.387	0.374	
PA	0.416	0.389	3150	SA	0.383	0.360	3050
ΓA	0.410	0.374	3150	SA	0.370	0.351	3950
	0.422	0.379			0.374	0.366	
	0.438	0.440			0.402	0.423	
DM4	0.430	0.421	2150	CNA	0.397	0.406	2050
PM	0.444	0.426	3150	SM	0.382	0.397	3950
	0.454	0.446			0.386	0.413	

ullet Tolerance on each color bin (x , y) is \pm 0.01

Dominant Wavelength Bin Structure

Color	Bin Code	Minimum Dominant Wavelength (nm)	Maximum Dominant Wavelength (nm)
	А	515	520
Green	1	520	525
Giccii	2	525	530
	3	530	535
	А	455	460
Blue	1	460	465
Dide	2	465	470
	3	470	475
	2	587.0	589.5
Amber	4	589.5	592.0
ATTIOCI	6	592.0	594.5
	7	594.5	597.0
Red	2	613.5	620.5
Reu	4	620.5	631.0

ullet ProLight maintains a tolerance of \pm 1nm for dominant wavelength measurements.

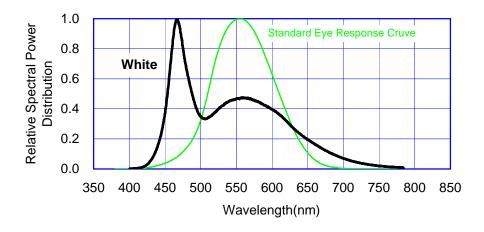
Forward Voltage Bin Structure

Color	Bin Code	Minimum Voltage (V)	Maximum Voltage (V)
	Α	2.85	3.10
	В	3.10	3.35
White	D	3.35	3.60
	Е	3.60	3.85
	F	3.85	4.10
	Α	2.85	3.10
	В	3.10	3.35
Warm White	D	3.35	3.60
	E	3.60	3.85
	F	3.85	4.10
	Α	2.85	3.10
	В	3.10	3.35
Green	D	3.35	3.60
	Е	3.60	3.85
	F	3.85	4.10
	Α	2.85	3.10
	В	3.10	3.35
Blue	D	3.35	3.60
	E	3.60	3.85
	F	3.85	4.10
	Α	1.75	2.00
	В	2.00	2.25
Amber	D	2.25	2.50
	Е	2.50	2.75
	F	2.75	3.00
	Α	1.75	2.00
	В	2.00	2.25
Red	D	2.25	2.50
	E	2.50	2.75
	F	2.75	3.00

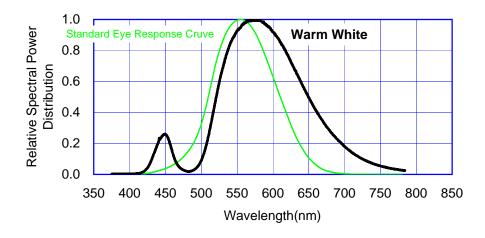
ullet ProLight maintains a tolerance of \pm 0.1 for Voltage measurements.

Color Spectrum, $T_J = 25$ °C

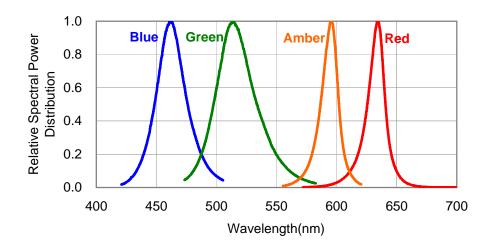
1. White



2. Warm White



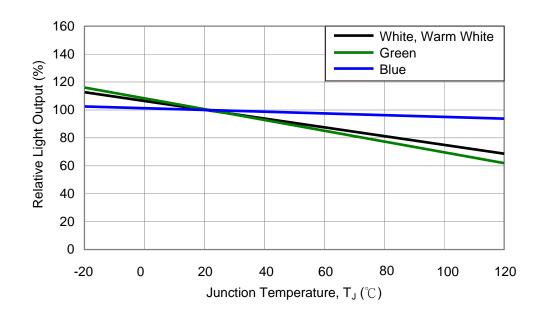
3. Blue · Green · Amber · Red

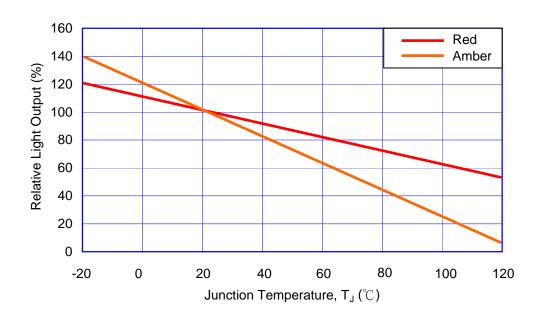


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Light Output Characteristics

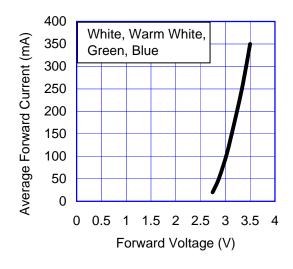
Relative Light Output vs. Junction Temperature at 350mA

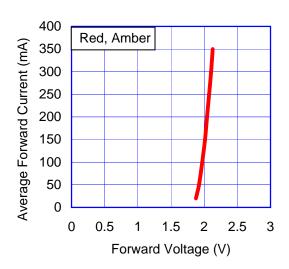




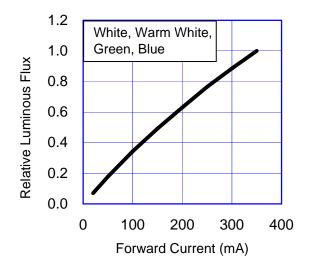
Forward Current Characteristics, T_J = 25°C

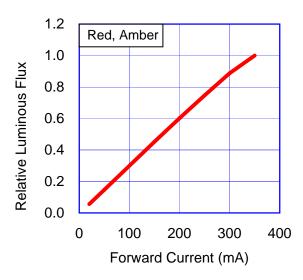
1. Forward Voltage vs. Forward Current





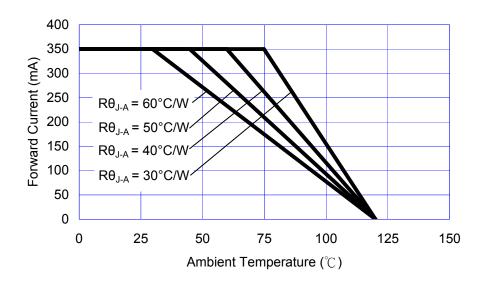
2. Forward Current vs. Normalized Relative Luminous Flux



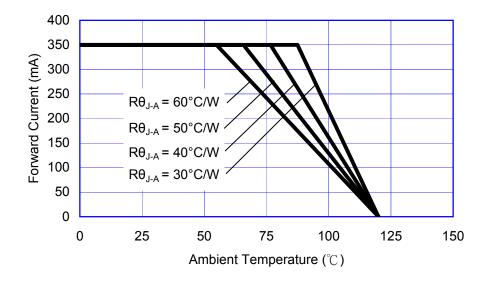


Ambient Temperature vs. Maximum Forward Current

1. White, Warm White, Green, Blue (T_{JMAX} = 120°C)

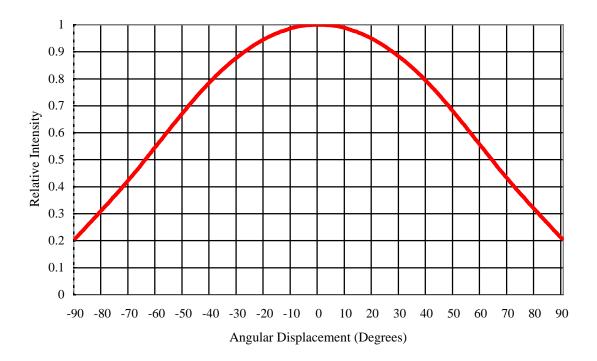


2. Red, Amber $(T_{JMAX} = 120$ °C)



Typical Representative Spatial Radiation Pattern

Lambertian Radiation Pattern



Qualification Reliability Testing

Stress Test	Stress Conditions	Stress Duration	Failure Criteria
Room Temperature Operating Life (RTOL)	25°C, I _F = max DC (Note 1)	25°C, I _F = max DC (Note 1) 1000 hours	
Wet High Temperature Operating Life (WHTOL)	85°C/60%RH, I _F = max DC (Note 1)	1000 hours	Note 2
Wet High Temperature Storage Life (WHTSL)	85°C/85%RH, non-operating	1000 hours	Note 2
High Temperature Storage Life (HTSL)	110°C, non-operating	1000 hours	Note 2
Low Temperature Storage Life (LTSL)	-40°C, non-operating	1000 hours	Note 2
Non-operating Temperature Cycle (TMCL)	-40°C to 120°C, 30 min. dwell, <5 min. transfer	200 cycles	Note 2
Non-operating Thermal Shock (TMSK)	-40°C to 120°C, 20 min. dwell, <20 sec. transfer	200 cycles	Note 2
Mechanical Shock	1500 G, 0.5 msec. pulse, 5 shocks each 6 axis		Note 3
Natural Drop	On concrete from 1.2 m, 3X		Note 3
Variable Vibration Frequency	10-2000-10 Hz, log or linear sweep rate, 20 G about 1 min., 1.5 mm, 3X/axis		Note 3
Solderability	Steam age for 16 hrs., then solder dip at 260°C for 5 sec.		Solder coverage on lead

Notes:

1. Depending on the maximum derating curve.

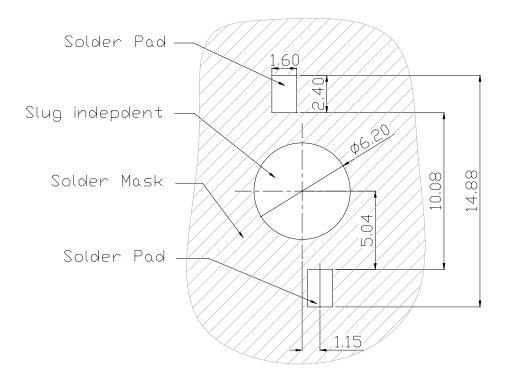
2. Criteria for judging failure

Item	Test Condition	Criteria for Judgement		
Item	rest Condition	Min.	Max.	
Forward Voltage (V _F)	I _F = max DC	-	Initial Level x 1.1	
Luminous Flux or Radiometric Power (Φ_V)	I _F = max DC	Initial Level x 0.7	-	
Reverse Current (I _R)	V _R = 5V	-	50 μA	

^{*} The test is performed after the LED is cooled down to the room temperature.

3. A failure is an LED that is open or shorted.

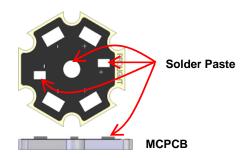
Recommended Solder Pad Design



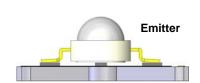
- All dimensions are in millimeters.
- Electrical isolation is required between Slug and Solder Pad.

Heat Plate Soldering Condition

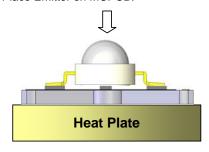
(1) Soldering Process for Solder Paste



Use Solder Mask to print Solder Paste on MCPCB.



Place Emitter on MCPCB.

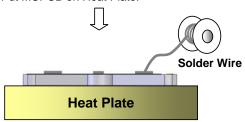


Put MCPCB on Heat Plate until Solder Paste melt. The Solder Paste sould be melted within 10 seconds. Take out MCPCB out from Heat Plate within 15 seconds.

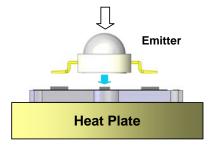
(2) Soldering Process for Solder Wire



Put MCPCB on Heat Plate.



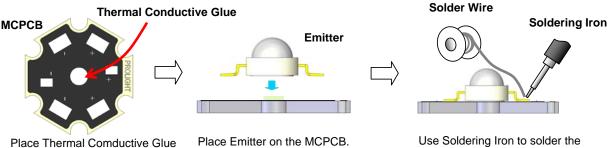
Place Solder Wire to the solder pad of MCPCB.



Put Emitter on MCPCB. Take the MCPCB out from Heat Plate within 10 seconds.

- Heat plate temperature: 230°C max for Lead Solder and 230°C max for Lead-Free Solder.
- We recommend using the 58Bi-42Sn eutectic alloy for low-temp. and lead free soldering (melting point = 138 °C).
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

Manual Hand Soldering

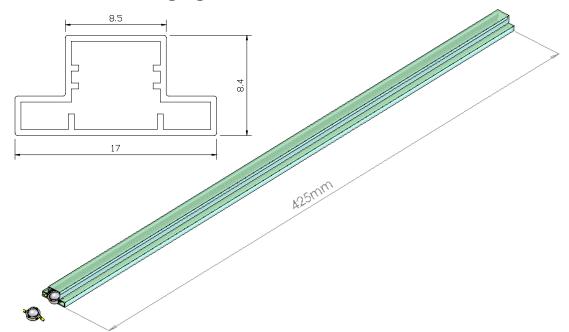


- on the MCPCB.

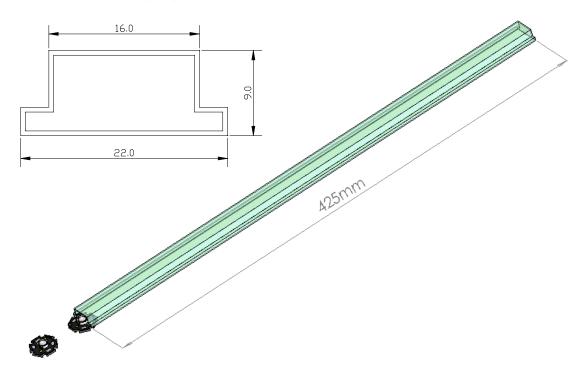
Use Soldering Iron to solder the leads of Emtter within 5 seconds.

- For prototype builds or small series production runs it possible to place and solder the emitters by hand.
- Solder tip temperature: 230°C max for Lead Solder and 260°C max for Lead-Free Solder.
- Avoiding damage to the emitter or to the MCPCB dielectric layer. Damage to the epoxy layer can cause a short circuit in the array.
- Do not let the solder contact from solder pad to back-side of MCPCB. This one will cause a short circuit and damage emitter.

Emitter Tube Packaging



Star Tube Packaging



Notes:

- 1. Emitter 50 pieces per tube and Star 20 pieces per tube.
- 2. Drawing not to scale.
- 3. All dimensions are in millimeters.
- 4. All dimendions without tolerances are for reference only.

^{**}Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing ProLight's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30°C and humidity less than 40% RH.

Precaution for Use

- Storage
 - Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing ProLight's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30°C and humidity less than 40% RH. It is also recommended to return the LEDs to the MBB and to reseal the MBB.
- The slug is is not electrically neutral. Therefore, we recommend to isolate the heat sink.
- The slug is to be soldered. If not, please use the heat conductive adhesive.
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.
- Please avoid rapid cooling after soldering.
- Components should not be mounted on warped direction of PCB.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When cleaning is required, isopropyl alcohol should be used.
- When the LEDs are illuminating, operating current should be decide after considering the package maximum temperature.
- The appearance, specifications and flux bin of the product may be modified for improvement without notice. Please refer to the below website for the latest datasheets. http://www.prolightopto.com/